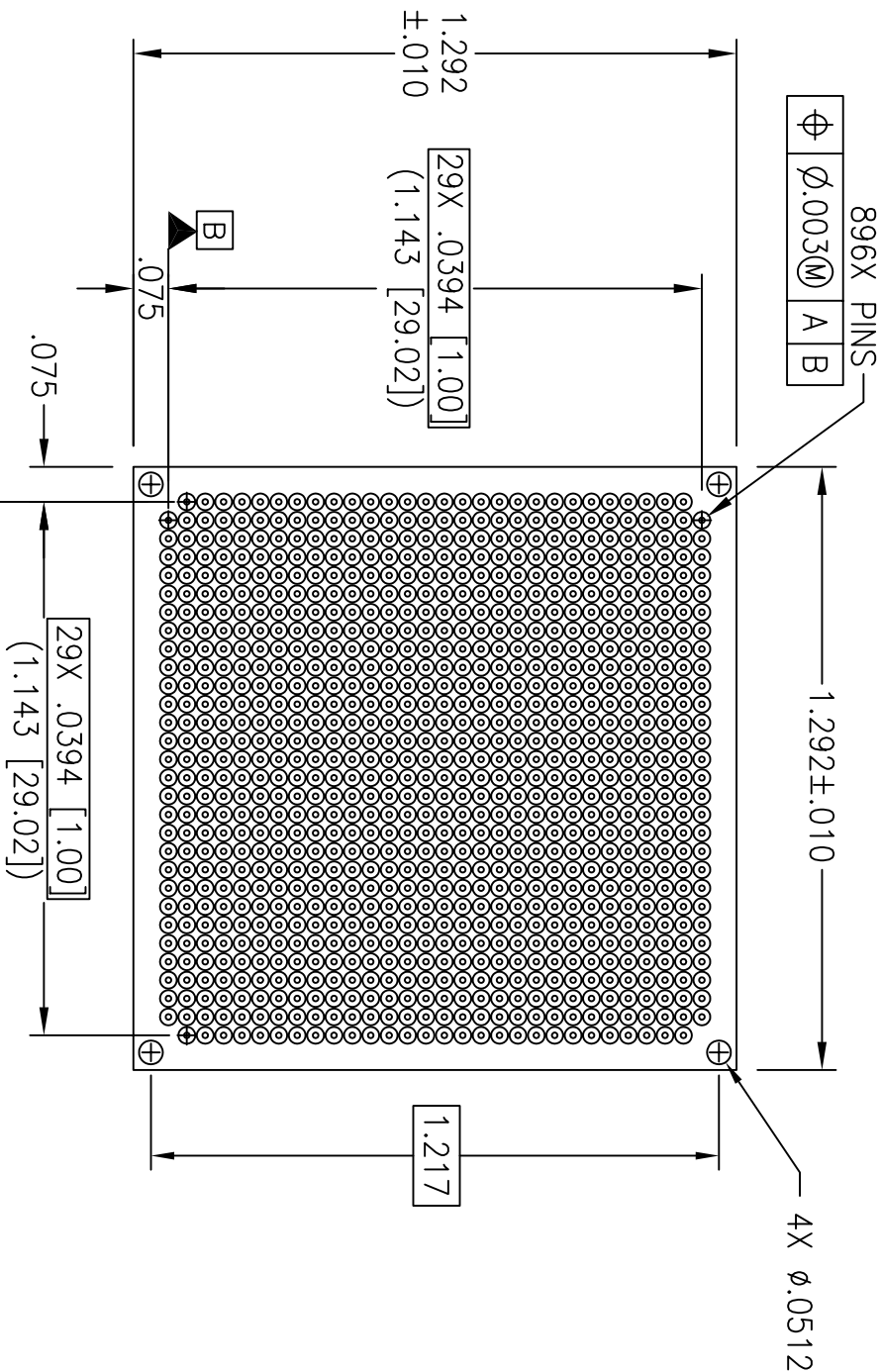


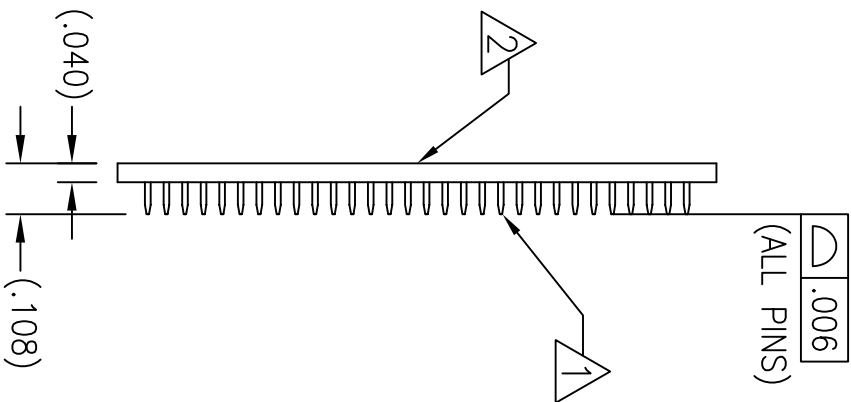
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REV	DESCRIPTION	ECN	DATE	RELEASE
1	SALES RELEASE			

TOP VIEW



RS VIEW



NOTES:

1. PINS Ø.0117
MATERIAL: PHOSPHOR BRONZE.
PLATING: HARD GOLD OVER NICKEL.
2. INSULATOR MATERIAL: FR4.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: FINISHES: DECIMALS: .XXX ±.005 .XXXX ±.0005

CONTRACT NO.		DRAWN BY		DATE	
DESIGNER		CHECKER		DATE	
PROCESS ENG.		DATE		DATE	
TITLE		SCALE		DRAWING NO.	
HIL0-BGA PIN BASE		N/A		HLP-300896-B-10	
30 X 30, 896 PINS		1mm PITCH		REV 1	
708 VIA ALONDRA, CAMARILLO, CA 93012		FINISHED ASST: HLP-300896-B-10		SHEET 1 OF 1	

ASIZE

4

3

2

1